



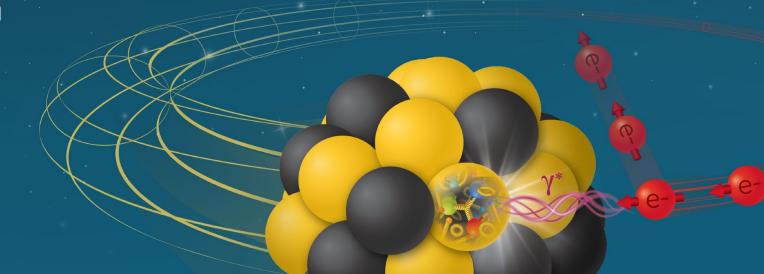
ePIC Backward EM calorimeter (EEEMCAL) status

Tanja Horn (CUA/JLab), DSL

Carlos Munoz-Camacho (IJCLab-Orsay), DSTC

for the EEEMCAL Consortium

10th EIC DAC Review June 11th – 13th, 2025

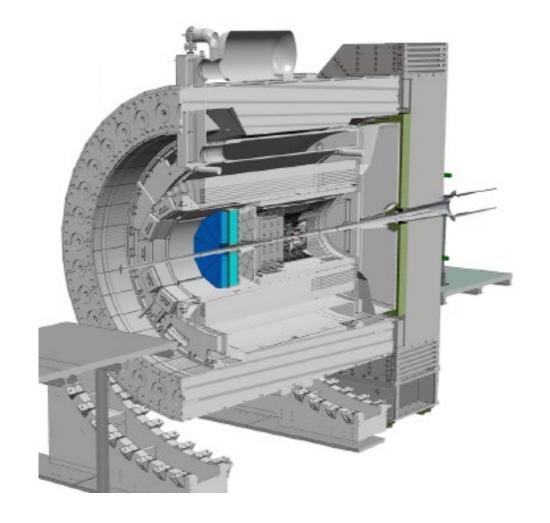


Charge Questions

- Is the design of the ePIC detector and its sub-systems appropriate and progressing well?
- Are the remaining work and technical, cost and schedule risks adequately understood?
 Are there opportunities?
- Will the detector be technically ready for baselining by late 2025?
- Are the detector integration and planning for installation and maintenance progressing well? Are there areas where further ideas should be pursued?
- Will the detector be ready for start of construction by late 2026?

EEEMCAL Major Components

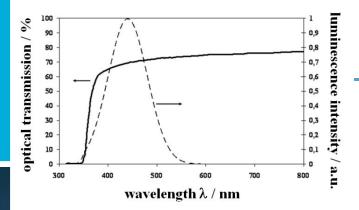
- □ Radiator consisting of scintillating lead tungstate (PWO) crystals and a thin reflector wrapping. The physics requirements for electron identification and detection dictate the main requirements for the radiator.
- □ Photosensors consisting of multi-pixel photon counters (MPPC) grouped into an array to maximize the surface coverage of the PWO blocks.
- Mechanical structure, including installation fixtures and a cooling system providing thermal stabilization, which is important for crystal performance.
- ☐ Signal Processing/DAQ providing the front-end electronics to transmit the signals to the data analysis modules.
- ☐ Simulations/Software providing the software libraries and infrastructure foundation for extracting the physics from the detector.



EEEMCAL Status Summary

Status ☐ FDR PWO crystals – completed ☐ FDR MPPC – completed ☐ Detailed mechanical design – approaching 80% ☐ Front End Readout – at different stages ☐ Engineering article test runs – multiple prototype beam tests completed, engineering articles complete and last phase of beam tests ongoing ☐ CD3A QA on PWO crystals – first (140) articles passed QA ■ Assembly and Installation planning - ongoing Items for 2025 ☐ EEEMCAL FDR – plan for this Fall after completion of further scheduled DESY and JLab beam tests ☐ Finalize mechanical design ☐ Finalize front-end electronics (FEE) and associated cooling design ☐ Final cooling implementation depends on final beam tests for FEE readout choice ☐ Continue CD3A (and in 2026+ also CD3B) QA on PWO crystals

Electron-Ion Collider



- Smaller decay time fast timing
 - > LY (100ns)/LY(1us) specification
- ☐ Optimizing the light yield relies on crystal transmittance in the near UV region
 - longitudinal transmittance specification
 - Transmittance spectrum in agreement with photosensor curve
- □ Require homogeneous collection of scintillation light along the crystal
 - > specification on transverse transmittance
- Mechanical specifications important for assembly, e.g., to minimize gaps
- □ Raw materials used impact crystal performance QA with vendor

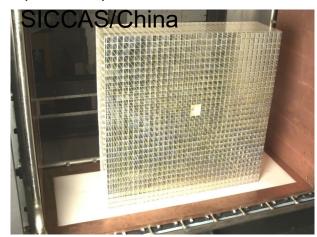
PbWO₄ specifications are similar to those achieved for JLab Projects (NPS, FCAL)

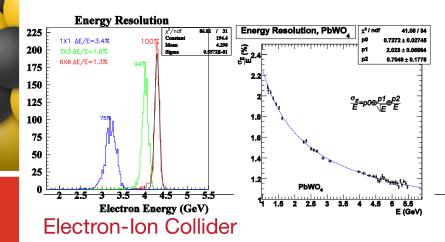
PWO Specifications

Parameter	Unit	EEEMCAL	Q&A Inform.	
		Required	Source	
Light Yield (LY) at RT	pe/MeV	≥15	Test with γ-source	
(for all sides polished crystals)				
LY(100ns)/LY(1µs)	%	>90	Test with γ-source	
Longitudinal Transmission			Optical	
at λ=360 nm	%	≥35	Measurement	
at λ=420 nm	%	≥60		
at λ=620 nm	%	≥70		
Transverse Transmission and LY	%	10	Optical	
uniformity along crystal			Measurement	
Inhomogeneity of Transverse	nm	≤5	Optic. Measure.	
Transmission Δλ at T=50%				
Induced radiation absorption			Irradiate with	
coefficient Δk at λ =420 nm and RT, for	m ⁻¹	<1.5	different sources	
integral dose >100 Gy				
Mean value of dk	m ⁻¹	≤1.0	Test	
Tolerance in Length	μm	≤±0,-100	Measure.	
Tolerance in sides	μm	≤±50		
Surface polished, roughness Ra	μm	≤0.02	Vendor	
Tolerance in Rectangularity (90°)	degree	≤0.1	Measure.	
Purity specific. (raw material)			Vendor	
Mo contamination	ppm	<10	Vendor	
La, Y, Nb, Lu contamination	ppm	?	5 Vendor	

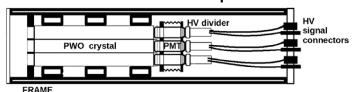
Crystal Beam Test Campaigns at JLab

HyCal (pre-2014) 1152 PbWO₄ crystals (PWO-I)

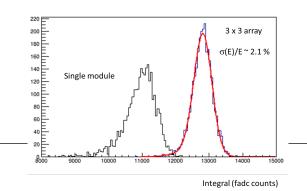




3x3 prototypes (2018/19) PbWO₄ (PWO-II) crystals CRYTUR/Czech Rep.

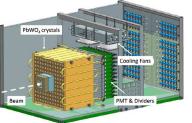


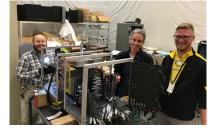


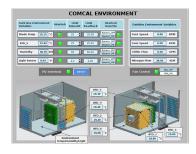


12x12 prototypes (2019) 144 PbWO₄ (PWO-II) crystals CRYTUR/Czech Rep/

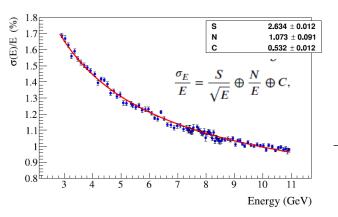












PWO Quality Assurance Protocol

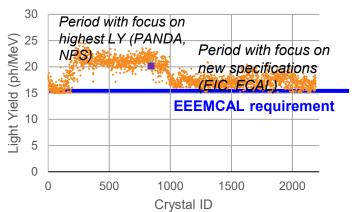
- PWO crystals are CD3A item
- ☐ First articles (140 crystals) passed QA
- □ Additional 110 crystals arrived at JLab end of May 2025 awaiting QA
- ☐ The QA builds on the process developed for NPS and consists of:
 - > 2 step visual inspection
 - mechanical dimension measurement
 - > light yield measurement
 - Kinetics
 - > transmittance measurement
 - > induced radiation absorption coefficient.



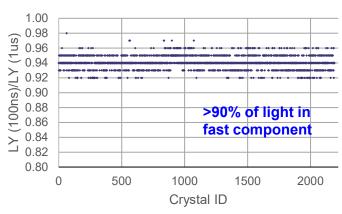


Characterization results of CRYTUR produced crystals (2017 - present)

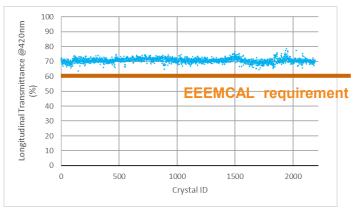


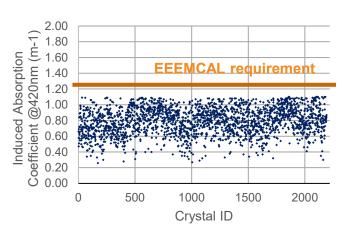


Kinetics



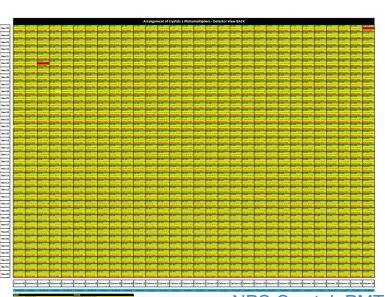
Longitudinal Transmittance

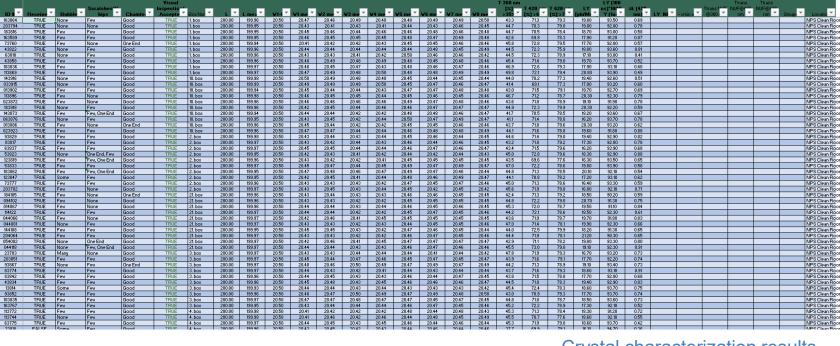




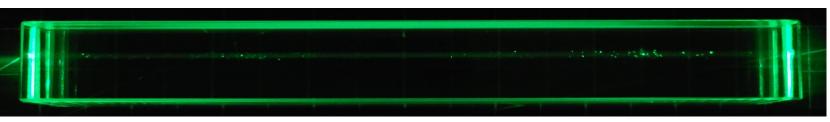
PWO Quality Assurance Documentation

Crystal quality assurance results are documented in a central location with a <u>master spreadsheet</u>





Crystal characterization results



Crystal images are documented along with the numerical characteristic

NPS Crystal+PMT+Cable module map

Mechanical Design Overview

Physics Considerations

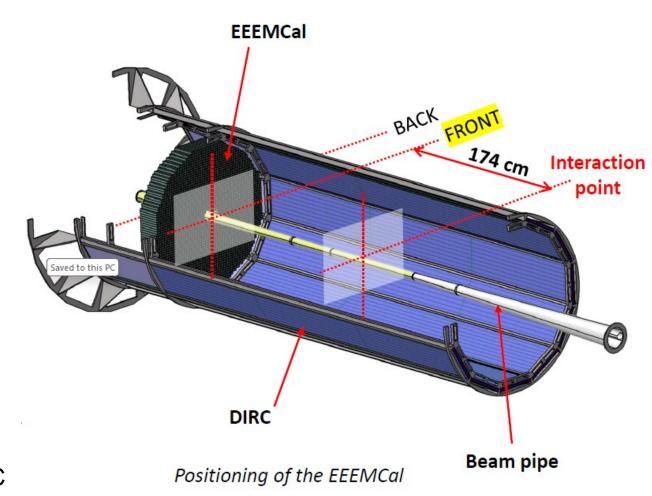
- Distance interaction point/EEEMCal = 174 cm
- Minimize the material & space between crystals
- Be as close as possible to the beampipe
- Optimize radiation lengths in front of the detector as possible, e.g., material budget is a consideration for the pfRICH (not shown)

Thermal Considerations

- Good stability of the room temperature around 23°C
- Temperature stability for crystals to within 0.1°C
- About 1500 W to dissipate

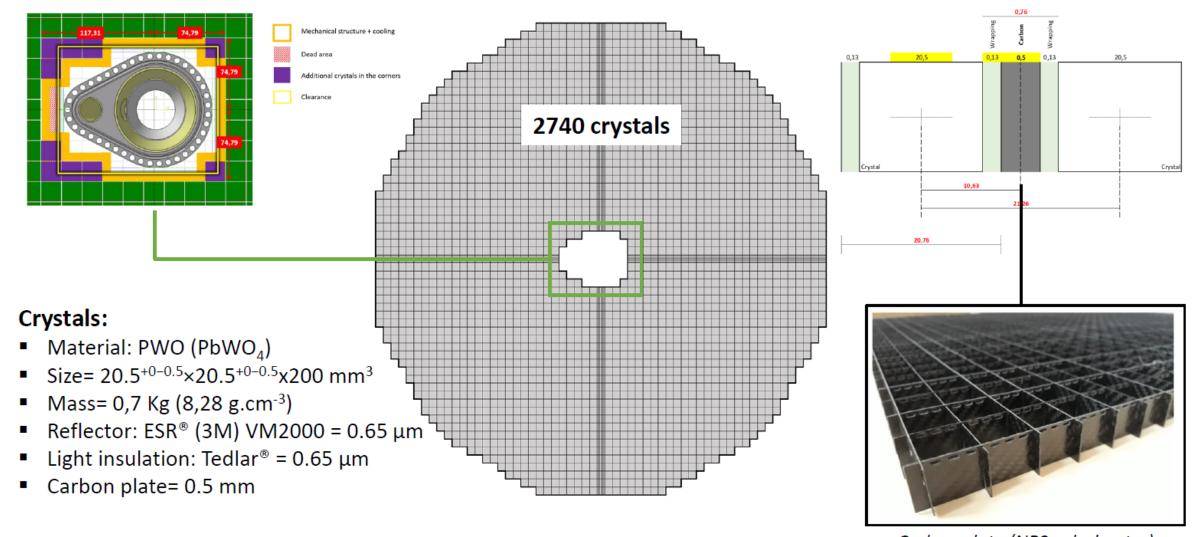
Installation Considerations

Removing the detector in one block Respect clearance between beam pipe and the DIRC



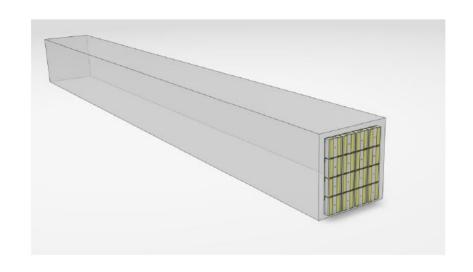
Crystal Configuration

Crystal configuration is defined Main clearances are defined

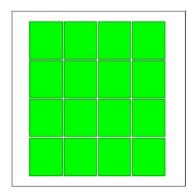


Carbon plate (NPS calorimeter)

MPPC Configuration and Coupling to Crystal





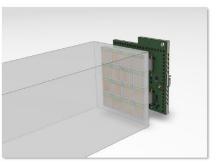




Optical grease



Daughter board – PCB connectors



Assembly Crystal + PCB

Choice of MPPC done

MPPC

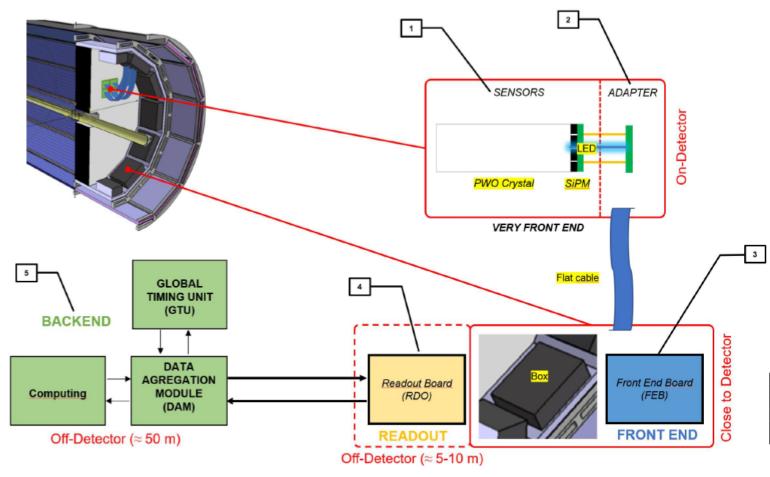
- ☐ Active surface 3mm x 3mm
- ☐ External size: 4.35mm x 3.85mm
- ☐ Reference: S14160-3015PS
- ☐ 16 MPPC per crystal → 43840 MPPC
- ☐ Space between MPPC: 0.2mm
- ☐ Surface covered by MPPC: ~34%

☐ Coupling to Crystal (Very Front End)

- ☐ 4x4 MPPC coupled with optical grease
- ☐ 1 PCB with the MPPC welded
- ☐ 1 PCB with the output connecter plugged on the PCB MPPC

Readout/DAQ Overview

Work on FEE ongoing
Location of power depends on FEE

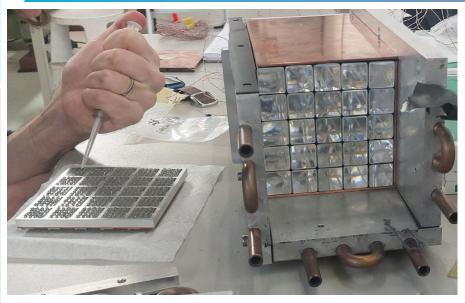


To keep in mind:

- Location of the power: into the FEB & the RDO
- No power on the very front end (+10W for SiPM after one year)
- Current discussion on the design of the FEB

n°	Designation	Description	In charge
1	SENSORS	SiPM	CUA, collaboration
2	ADAPTER	PCB SiPM	IJCLab, OMEGA
3	Front End Board (FEB)	ASIC	Oakridge, LLR, OMEGA
4	Readout Board (RDO)	FPGA	BNL, LLR
5	BACKEND	GTU, DAM, Computing	BNL

DESY beam test (spring 2025)

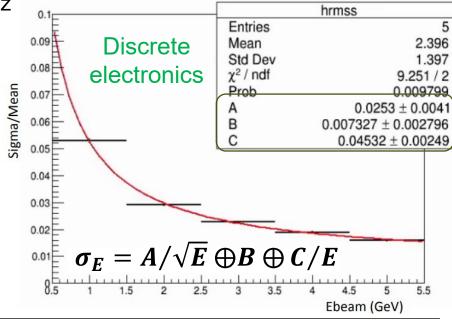


- 25 PWO crystals from CRYTUR
- SiPM readout
- Cooling and temp control
- 1 5 GeV electron beam through a 2x2 mm² collimator
- Triggered by 2 scintillators
- Typical DAQ rates: ~50-100 Hz

- Two readout option tested:
- ➤ Readout with H2GCROC3b chip
- Preamp board & CAEN V1725S 14-bit 250MS/s digitizers

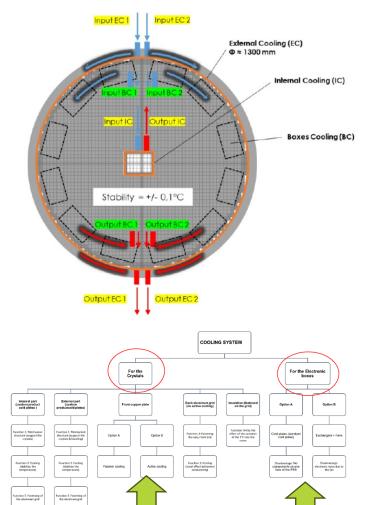
- Successful readout of all 400 channels with both set of electronics
- ➤ Significant noise (1/E) term in the energy resolution not yet understood:
 - Likely PS instability due to large capacitance of sensors
 - H2GCROC3b electronics suffered some additional issues (eg. poor grounding in some adaptor boards)
 - Potential light leaks or beam energy spread (under investigation)

Upcoming 2nd campaign at DESY this Fall with improved setup



Cooling Overview and Requirements

Cooling environment is known



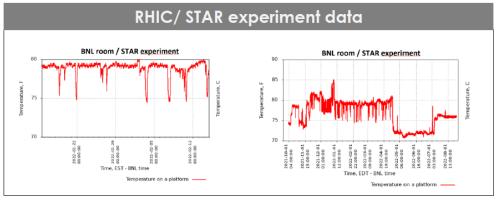
3 main parameters for the sizing:

- The amplitude of the temperature variations in the experimental hall
- The frequency/period of the temperature variations in the experimental hall ——→
- The location of the power to dissipate

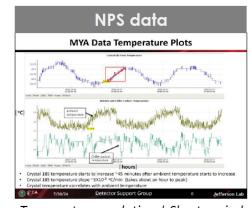


6 hours < T < 12 hours

Power on electronic boxes



Temperature evolution | Long period



Temperature evolution | Short period

_{2 main objectives:} cooling

cooling

Electronics

Stabilize the temperature of the crystals to within 0,1°C

Crystal

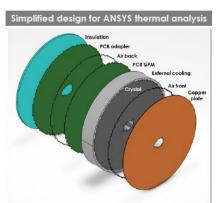
• Dissipate the power of the FEB (& RDO) \approx 1500 W

Thermal Simulations

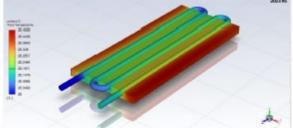
Thermal simulations with advanced design available

Compare two Steady States

Simple Model



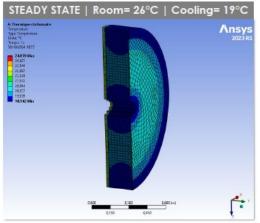
Check impact of room temperature variation and insulation



Fluent simulation of a cold plate to validate the homogeneity of the cooling

External and internal cooling at the same temperature

Steady State



Exemple of results at 26°C Temperature distribution on the crystals

26°C → 23°C in 6 hours

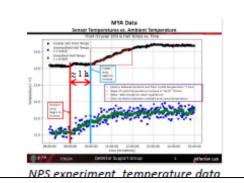
Start from the steady state at room= 26°C

T= 12 hours

Two steady states comparison

Results:

- ∆T (stabilty) < 0,1°C
- 1 hour < Shift (inertia) < 2 hours
- In accordance with the NPS data



Model:

- 1st simulation: Steady state with temperature room= 23°C
- 2nd simulation: Steady state with temperature room= 26°C
- → Comparison (worst case)

Results:

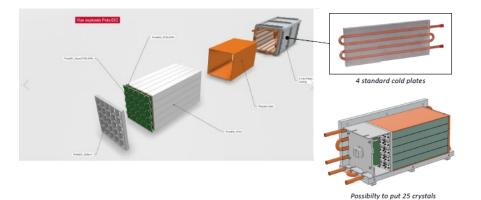
- Without insulation: ΔT (stabilty) = 1,6°C
- With insulation (foam, air and copper): ∆T (stability) = 0,4°C

Transient States Thermal Analysis | Insulating + Copper plate | Convection 26°C -> 23°C | 12 hou Room temperature Top Back Middle-1 Back Bottom Back Middle front & back Temperature stability

Evolution of the temperature for a variation of the room temperature from 26°C to 23°C in 6 hours and 23°C to 26°C in 6 hours

Thermal Tests

Room Temperature Tests



Results eat ON - Chiller OFF

eat ON - Chiller ON

Heat OFF - Chiller ON

eat ON cycle - Chiller ON

at OFF - T chiller = 19°C → 0°C

Chiller Stability = +/- 0,1°C

8,83

0,07

0,03

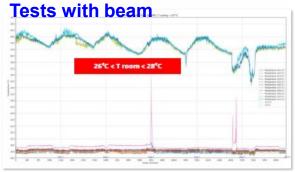
0,65

1,90

Without cooling Stability = +/-0,5°C

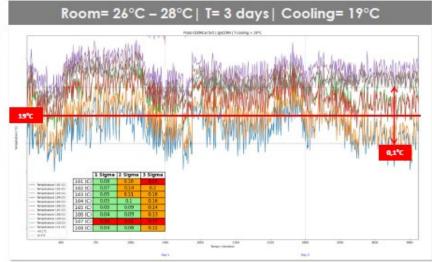
With cooling Stability = +/-0,1°C

Setup of the thermal with prototype 5x5 (with cooling)



Beam test @ CERN:

- Temperature stability under +/- 0,1°C
- Problem on one sensor (107, out of use)



Evolution of the temperature of the crystals during the beam test at CERN



Room= 19°C - 27°C | PCB= ON, OFF & Cycle | Cooling= ON & OFF

0.04

0,03

0,11

0,08

0,06

0,11

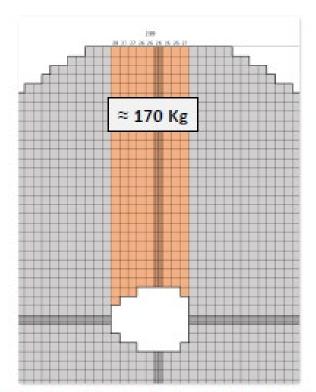
0,11

0,04

0,03

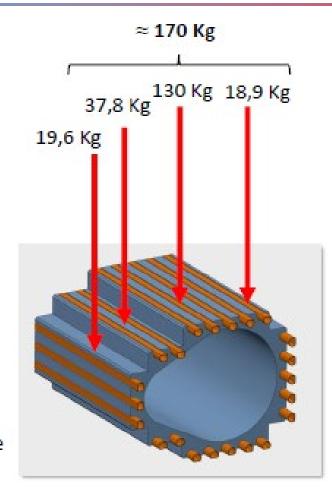
0,05

Mechanical Design – Internal Structure

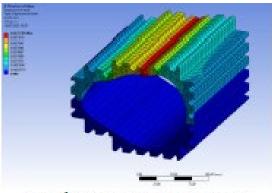


FEA (Finite Element Analysis) Model:

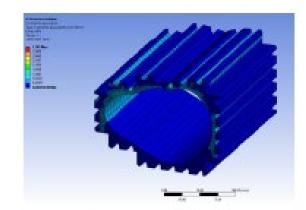
- 239 crystals stacked on the internal structure
- Without copper tubes for the FEA



Tanja Horn



Displacement < 0,01 mm



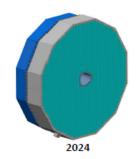
Stress < 3 Mpa

Mechanical Design – External Structure



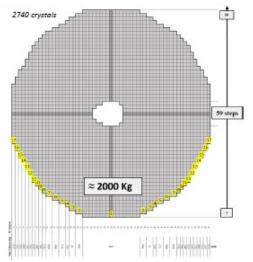
Assembly of rings and plates

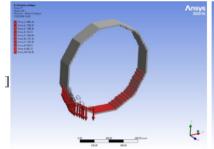
-	+
Assembly	Cheap
Cooling	
Stress & Deflection	



Monobloc - +

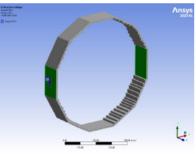
-	+
Expensive	Cooling
Production	Stress & Deflection
Corrosion	No assembly





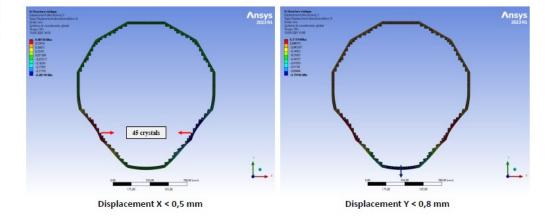
FEA Model:

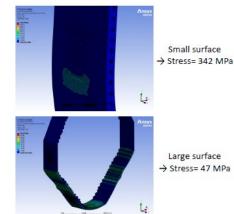
- 1 face at the center
- → 665 Kg
- 16 other faces on both sides
- → 626,5 Kg x2 (11,9 kg to 79,8 Kg)
- 59 steps to check the deflection during the assembly



FEA Model:

- Worst case: fastened at 3 and 9 o'clock
- The way to fasten the structure increase the results in terms of stress





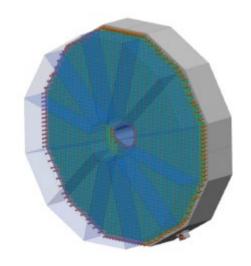
Results:

- Displacement X < 0,5 mm → No stress on the crystals (45 crystals +0,025)
- Displacement Y < 0,8 mm for the worst case
- Displacement Y = 0,36 mm for step 26 (just before the assembly of the internal structure)
- Stress: Optimization required

Results of FEA are encouraging
Perform FEA simulation with advanced design
Choose means of production for structures
(machining or foundry)

Electron-Ion Collider

Mechanical Design – Assembly

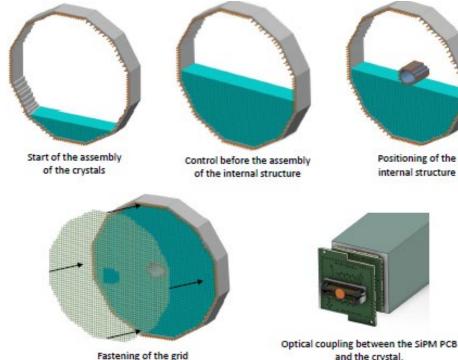


List of materials to install:

- Crystals
- Mechanical structures (internal & external)
- Grid (fastening of the PCB)
- Copper plate, Insulation
- Cooling
- Electronic boxes, Cables

Geographical location:

- Crystals → USA
- Mechanics, cooling → France
- Electronics, cables → France (a priori)
- Transport by plane in flight-cases



Procedure ongoing Depends on very front-end and FEB Assembly test at IJCLab Still deciding on the final assembly at JLab or BNL

Assembly of the electronic boxes +

insulation (back) and copper plate (front)

Control after the assembly

of the internal structure

Options considered for the assembly:

- Pre assembly without crystals @IJCLab (Orsay, France)
- Assembly @Jlab or/and @BNL

End of the assembly

of the crystals

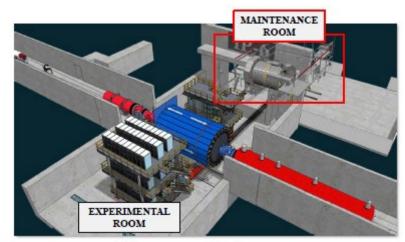
Ready to: Cabling, tubing

INTEGRATION

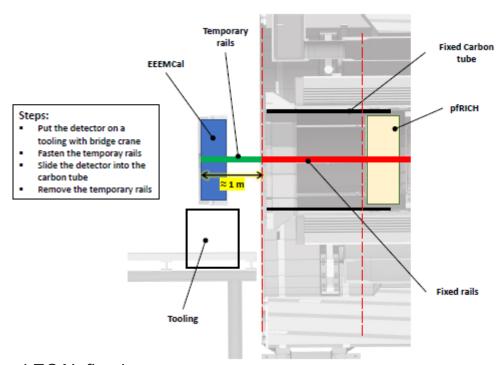
and the crystal.

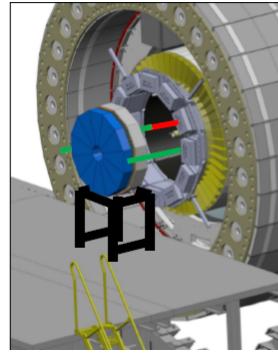
Quality control by the other side (front)

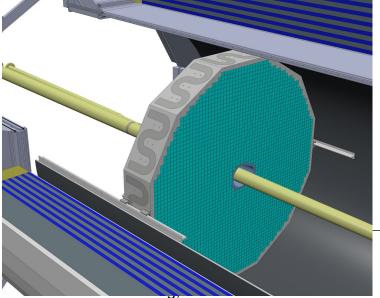
Mechanical Design – Installation



Overview of the experimental and maintenance rooms







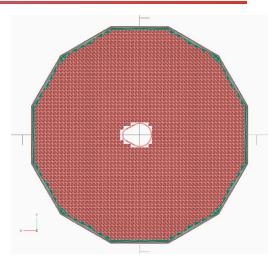
Backward ECAL fixed with rails to the GST (global support tube) in carbon fiber and showing the external cooling structure planned with FSW technology

Define positioning of the rails for insertion of detector Study handling of the detector Services depend on FEB and cooling

Software/Simulation Development

Software builds on experience from JLab projects (e.g., HYCAL, FCAL, NPS, etc.) Anticipated to follow a similar workflow Slow controls: HV monitoring Sample pulse amplitude 800 700 600 500 400 300 200 100 Column Number Online diagnostic plots NPS.cal.clusY:NPS.cal.clusE cnps_intlk_cz_t_ @:22.184 5.2.2 npsvme{2,3,4,5} 5.2.3 npsvtp{1,2,3,4,5} 6 VTP uBoot configuration

EEEMCAL in ePIC simulation framework



EEEMCAL performance

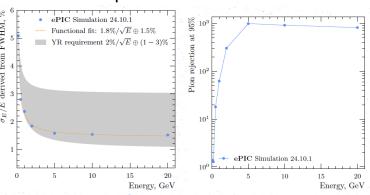
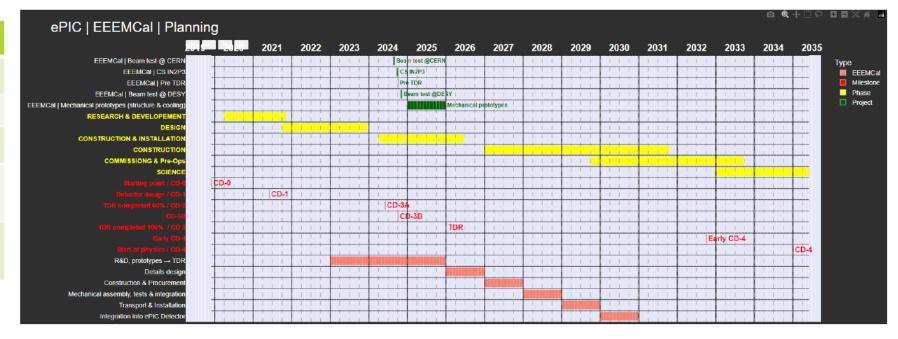


Figure 8.128: EEEMCal performance estimated from single particle simulations using the full ePIC detector geometry. Left: energy resolution as a function of the incident particle energy. Right: pion rejection factor as a function of energy and different values of electron

Organization and Development Overview

Item	Institutions
Crystals	CUA, UKY, JMU, MIT
MPPC	ACU, OU, Lehigh, FIU
Mechanical	IJCLab-Orsay
Signal Processing	IJCLab-Orsay, OU, ACU
Simulations and Software	AANL, UKY, AU, W&M



Front-End Board (FEB)

- → Location of the power to dissipate
- → Better estimation of the cables needed
- → Design of the FEB

Mechanical design:

- → Internal structure + cooling
- → External structure + cooling
- → FEA simulation with advanced design
- → Thermal simulation with advanced design

Installation requirements

- → Clearances
- → Location of the rails for the assembly
- → Services

Summary

□ Design of EEEMCAL is nearing 90% completion.
☐ Crystal first (140) articles have passed QA
☐ Remaining technical work in FEE is progressing well and expected to reach 90% mark soon
☐ Thermal simulations complete
☐ Multiple prototype beam tests completed, engineering articles complete and last phase of bear
tests ongoing
☐ Last aspects of integration (FEE and associated cooling) need to be finalized after test beam
completed
☐ Still deciding on final assembly at JLab or BNL
☐ EEEMCAL is on track to be technically ready for baselining at the end of the year

Electron-lon Collider

10th EIC DAC Meeting, June 11th – 13th 2025



Context for PbWO₄ Specifications

In general, for high-precision electromagnetic calorimetry, the following are of relevance:

- Smaller radiation length for smaller longitudinal size
- Smaller Moliere radius allowing higher granularity
- Smaller decay time
- Better energy resolution. Larger number of photoelectrons per MeV to reach higher resolution
- ➤ Smaller constant term contribution to energy resolution, mainly due to non-uniformity and gaps, to readout and noise. → for sensitivity checks need tests with detector prototypes in beam
- > Reasonable temperature dependence to light yield
- Higher radiation hardness (EM and/or hadron fluences)



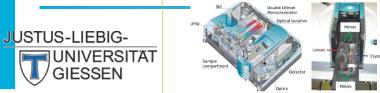
Parameter ===== Material	Density (g/cm ³)	Rad. Length (cm)	Moliere Radius (cm)	Decay time (ns)	Light Yield (γ/MeV)	dLY/dT (%/°C)	Rad. Hard. (krad)
NaI(Tl)	3.67	2.59	4.13	245	41000	-0.2	12
CsI(Tl)	4.51	1.86	3.57	1220	60000	0.4	1
CsI	4.51	1.86	3.57	35			1
BaF ₂	4.89	2.03	3.1	650 0.9	16000 2000		>50
CeF ₃	6.16	1.70	2.41	30	2800	~0.1	>100
(BGO) Bi ₄ Ge ₃ O ₁₂	7.13	1.12	2.23	300	8000 4000		
(PWO) PbWO ₄	8.3	0.89	2	30 10		-2.5	>1000
SciGlass	3.7-4.5	2.2-2.8	23	20-50	500-2000	None	>1000

PbWO₄ meets the requirements of an extremely fast, compact, and radiation hard scintillator material providing sufficient luminescence yield to achieve good energy resolution.

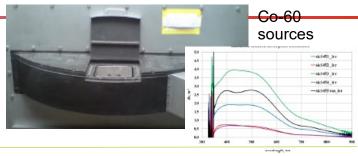
QA facilities at Universities Optical Transmittance (L/T)

Crystal light yield and timing

Radiation Hardness and recovery



Cs-137 source and calibrated 2-inch PMT (Hamamatsu R2059-01) with QE(420nm)=24%.

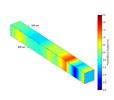






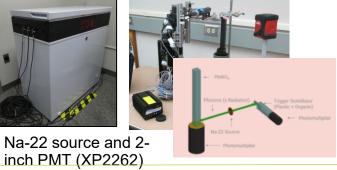
spectrometer

Modified Varian Cary 5000



Perkin-Elmer Lambda 950 spectrometer

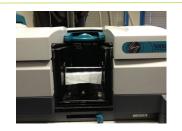






160)





Varian Cary 5000 spectrometer

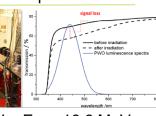


Cs-137 source and 2-inch PMT









Electrons 5.5 MeV < E_e < 16.6 MeV; adjust beam intensity to illumination with g rays (Co-60, 30 Gy)



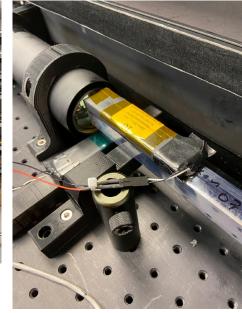
Electron-Ion Collider

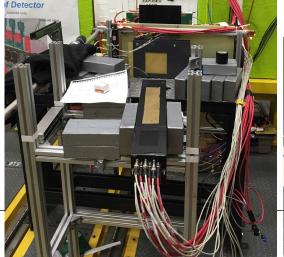
JLab crystal test facility for PbWO₄ QA and prototype

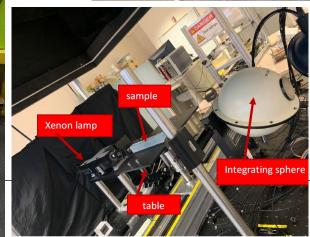
- □ Dedicated cleanroom facility for crystal characterization
 - Mitutoyo QM for mechanical dimensions measurements. Precise to 1 micron.
 - Crystal Light Yield measurements
 - Optical transmittance with integrating sphere
 - > Radiation hardness in beam
- □ Beam test facility with tagged photon beam up to 4-5 GeV
 - ➤ Technique demonstrated successfully for NPS can be adapted for EIC prototype tests











PbWO₄ crystal production for JLab Projects

Production of PWO crystals at CRYTUR – Turnov, Czech Republic

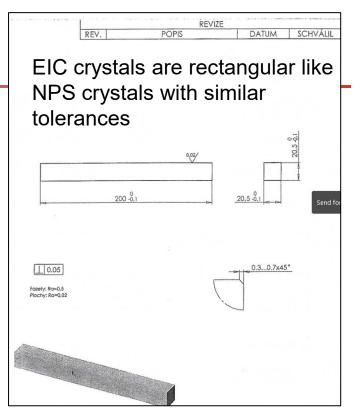
- long tradition in the production of inorganic scintillators. Restart of PWO production in 2014 production based on Czochralski technology



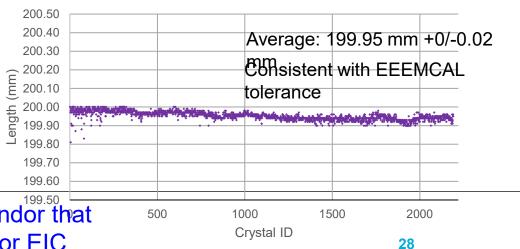


- → 2190 PWO crystals delivered continuously for projects at JLab since 2017
- ☐ Crystals used for both NPS and FCAL-2
- □ All 1100 NPS crystals for NPS passed the NPS quality assurance tests (similar for FCAL-2)





Length uniformity of CRYTUR crystals (2017 – present)



Electron-lon Collider CRYTUR is a well established and tested vendor that can deliver crystals of the quality needed for EIC